

描述 / Descriptions

SOD-123 塑封封装 肖特基二极管。
Schottky Diode in a SOD-123 Plastic Package.

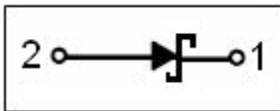
特征 / Features

高击穿电压, 低正向压降,。无卤产品。
High Breakdown Voltage, Low Forward Voltage, HF Product.

用途 / Applications

肖特基二极管。
Schottky diode.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1:Cathode PIN2:Anode

放大及印章代码 / h_{FE} Classifications & Marking

Marking	HS9
---------	-----

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	V
Working peak reverse voltage	V_{RWM}	100	V
Continuous Forward Current	I_F	150	mA
Repetitive peak forward current (Note 1) @ tp < 1.0s, Duty Cycle < 50%	I_{FRM}	350	mA
Non-reptitive Peak Forward Surge Current at 8.3ms	I_{FSM}	25	A
Power Dissipation	P_D	200	mW
Thermal resistance junction to ambient air	R_{thJA}	500	°C/W
Operating and Storage Temperature Range	T_J, T_{stg}	-55 ~ +150	°C

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
Reverse Breakdown Voltage at $I_R=100\mu A$ (NOTE 2)	$V_{(BR)R}$	$I_R=100\mu A$	100	V
Maximum Forward Voltage (NOTE 2)	V_F	$I_F=0.1mA$	0.3	V
		$I_F=10mA$	0.45	
		$I_F=250mA$	1.0	
Peak Reverse Current	I_R	$V_R=1.5V$	0.3	μA
		$V_R=10V$	0.5	
		$V_R=50V$	1	
		$V_R=75V$	2	
Diodes Capacitance	C_T	$V_R=0, f=1MHZ$	20	pF
		$V_R=1V, f=1MHZ$	12	

NOTES:

- (1) Part mounted on FR-4 board with recommended pad layout.
- (2) Short duration pulse test used to minimize self-heating effect.

电参数曲线图 / Electrical Characteristic Curve

Fig.1 Power Derating Curve

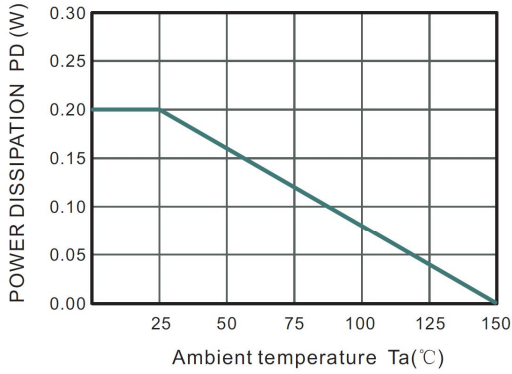


Fig.2 Typical Reverse Characteristics

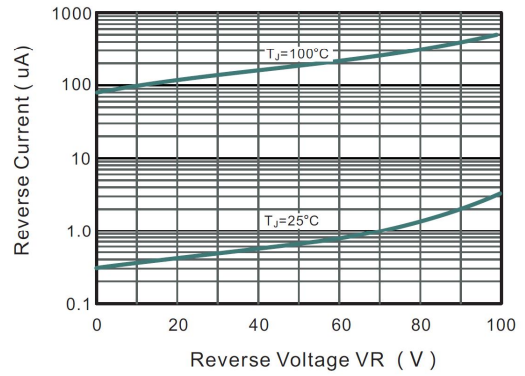


Fig.2 TYPICAL FORWARD VOLTAGE

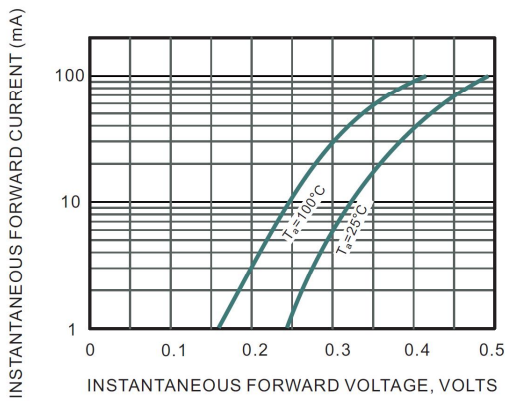


Fig.3 Typical Junction Capacitance

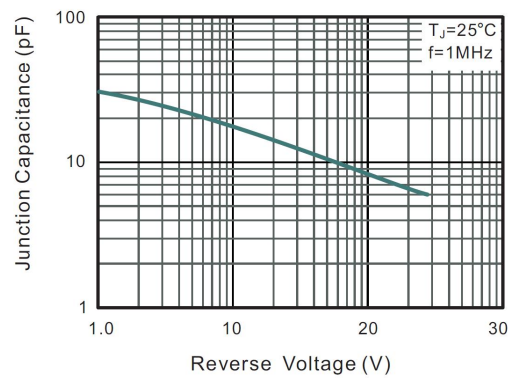


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

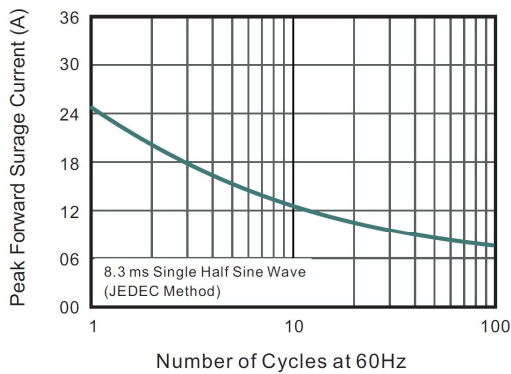
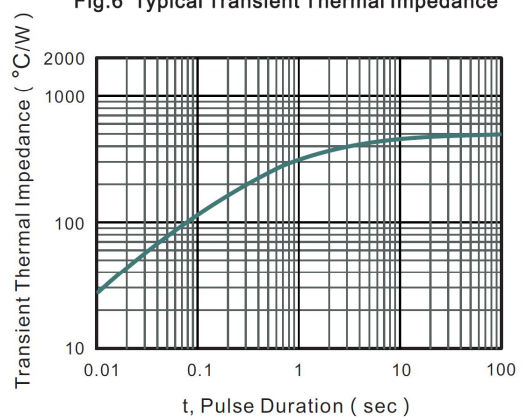
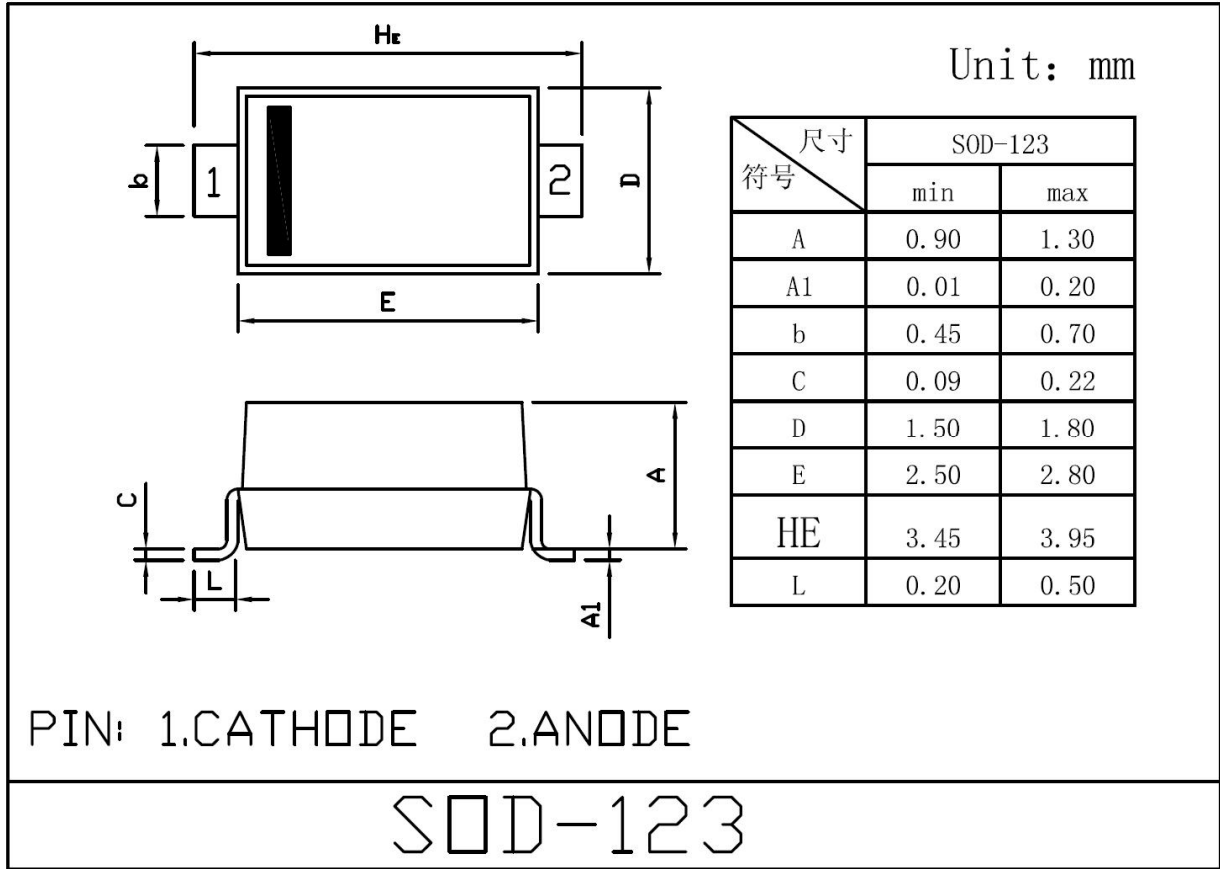


Fig.6 Typical Transient Thermal Impedance



外形尺寸图 / Package Dimensions



印章说明 / Marking Instructions



说明：

H： 为公司代码

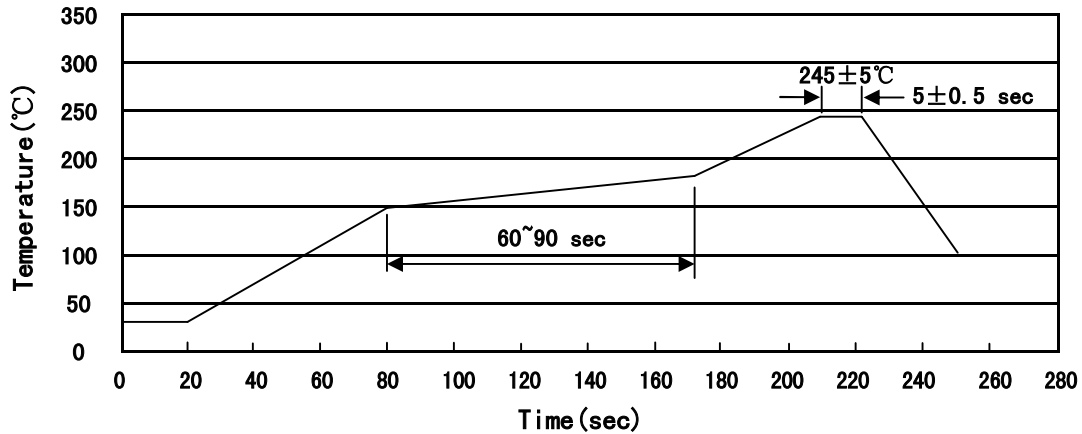
S9： 为型号代码

Note:

H: Company Code.

S9: Product Type.

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-123	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

使用说明 / Notices

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for [Schottky Diodes & Rectifiers](#) category:

Click to view products by [Blue Rocket](#) manufacturer:

Other Similar products are found below :

[MA4E2039](#) [MA4E2508M-1112](#) [MBR10100CT-BP](#) [MBR1545CT](#) [MMBD301M3T5G](#) [RB160M-50TR](#) [BAS16E6433HTMA1](#) [BAS 3010S-02LRH E6327](#) [BAT 54-02LRH E6327](#) [IDL02G65C5XUMA1](#) [NSR05F40QNXT5G](#) [NSVR05F40NXT5G](#) [NTE555](#) [JANS1N6640](#) [SB07-03C-TB-H](#) [SK310-T](#) [SK33A-TP](#) [SK34B-TP](#) [SS3003CH-TL-E](#) [PDS3100Q-7](#) [GA01SHT18](#) [CRS10I30A\(TE85L,QM](#) [MA4E2501L-1290](#) [MBRB30H30CT-1G](#) [JANTX1N5712-1](#) [SB007-03C-TB-E](#) [SK33B-TP](#) [SK35A-TP](#) [SK38B-LTP](#) [NTE505](#) [NTSB30U100CT-1G](#) [VS-6CWQ10FNHM3](#) [CRG04\(T5L,TEMQ\)](#) [ACDBA1100LR-HF](#) [ACDBA1200-HF](#) [ACDBA240-HF](#) [ACDBA3100-HF](#) [CDBQC0530L-HF](#) [ACDBA260LR-HF](#) [ACDBA1100-HF](#) [MA4E2502L-1246](#) [10BQ015-M3/5BT](#) [10BQ060-M3/5BT](#) [NRVB130LSFT1G](#) [CRS08TE85LQM](#) [PMAD1108-LF](#) [B120Q-13-F](#) [1N5819T-G](#) [B0530WSQ-7-F](#) [PDS1040Q-13](#)